

N-Channel Enhancement Mode Power MOSFET

Description

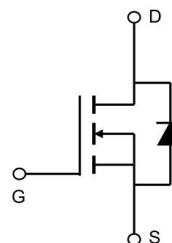
The PES016N08R uses deep trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

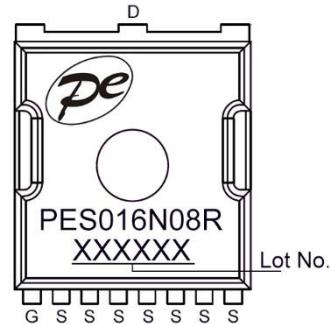
- $V_{DS} = 90V$, $I_D = 360A$
- $R_{DS(ON)} < 1.6m\Omega$ @ $V_{GS}=10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

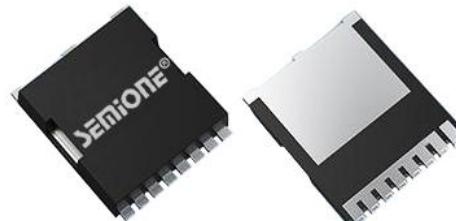
- DC/DC converter
- High frequency switching and synchronous rectification



Schematic diagram



Marking and pin assignment



TOLL

Absolute Maximum Ratings ($TC=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Rating | Unit |
|--|------------------------|------------|------|
| Drain-Source Voltage | V_{DS} | 90 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 360 | A |
| Drain Current-Continuous ($T_C=100^\circ C$) | $I_D(T_C=100^\circ C)$ | 275 | A |
| Pulsed Drain Current (Note 1) | I_{DM} | 1440 | A |
| Maximum Power Dissipation | P_D | 460 | W |
| Single Pulsed Avalanche Energy ($L=0.5mH$) | E_{AS} | 2500 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | °C |

Thermal Characteristic

| | | | |
|--|-----------------|-----|------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 0.3 | °C/W |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 45 | °C/W |

Electrical Characteristics (TC=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------|--|-----|------|-----------|-----------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 90 | 98 | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=80V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.6 | 3.3 | 4 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=50A$ | - | 1.3 | 1.6 | $m\Omega$ |
| Forward Transconductance | g_{FS} | $V_{DS}=10V, I_D=50A$ | - | 110 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=40V, V_{GS}=0V, F=1.0MHz$ | - | 8575 | - | pF |
| Output Capacitance | C_{oss} | | - | 1691 | - | pF |
| Reverse Transfer Capacitance (Note 4) | C_{rss} | | - | 35 | - | pF |
| Gate Resistance | R_g | $V_{DS}=0V, V_{GS}=0V, F=1.0MHz$ | - | 2.4 | - | Ω |
| Switching Characteristics | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DS}=40V, I_D=50A, V_{GS}=10V, R_G=5\Omega$ | - | 37 | - | nS |
| Turn-on Rise Time | t_r | | - | 32 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 95 | - | nS |
| Turn-Off Fall Time | t_f | | - | 30 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=40V, I_D=50A, V_{GS}=10V$ | - | 245 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 66 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 65 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{GS}=0V, I_S=10A$ | - | - | 1.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F=85A, dI/dt=100A/\mu s$ | | 105 | | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 310 | | nC |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to product.

Typical Electrical and Thermal Characteristics

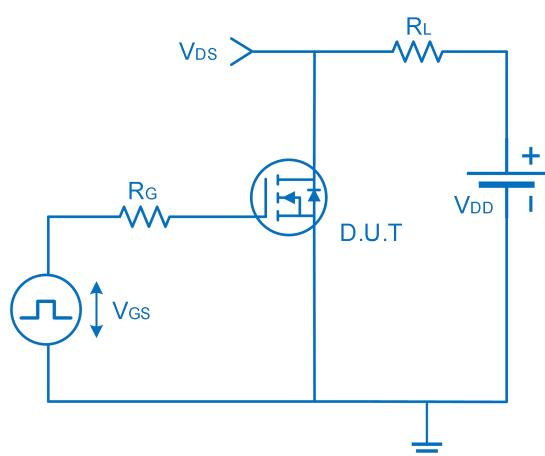


Figure 1 Switching Test Circuit

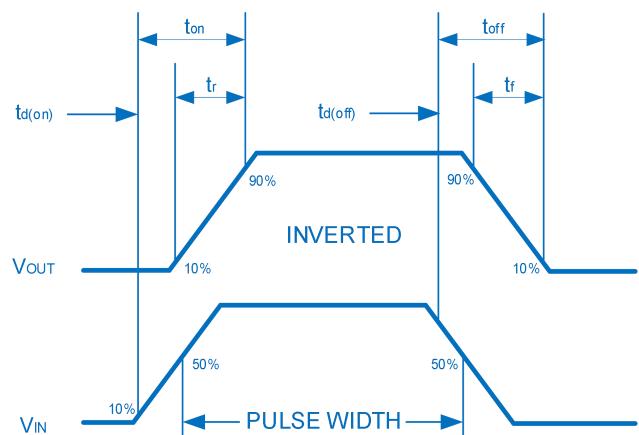
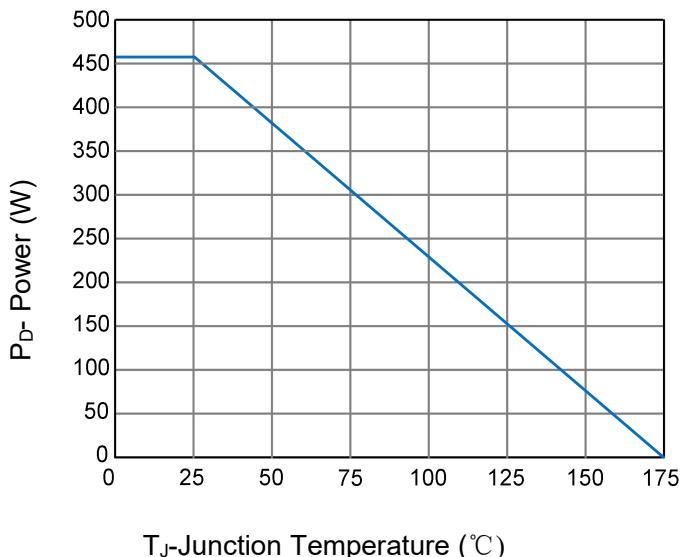
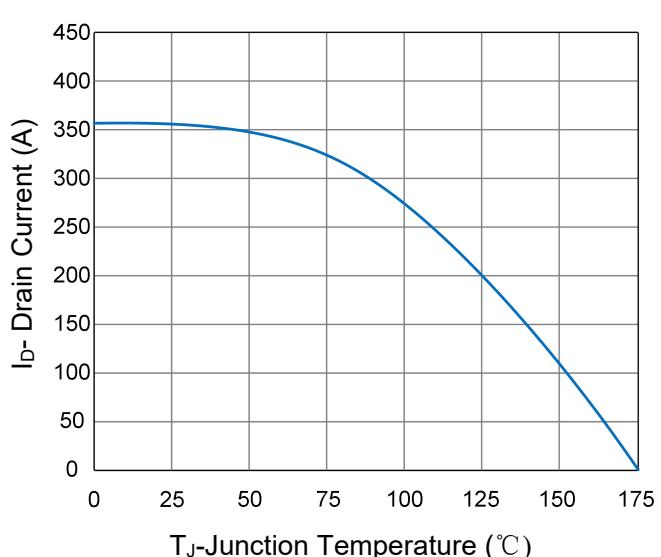


Figure 2 Switching Waveform



T_J-Junction Temperature (°C)

Figure 3 Power De-rating



T_J-Junction Temperature (°C)

Figure 4 Drain Current

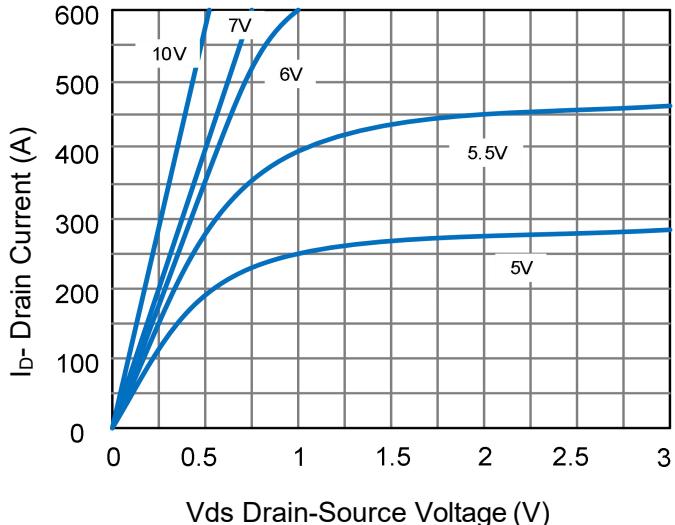


Figure 5 Output Characteristics

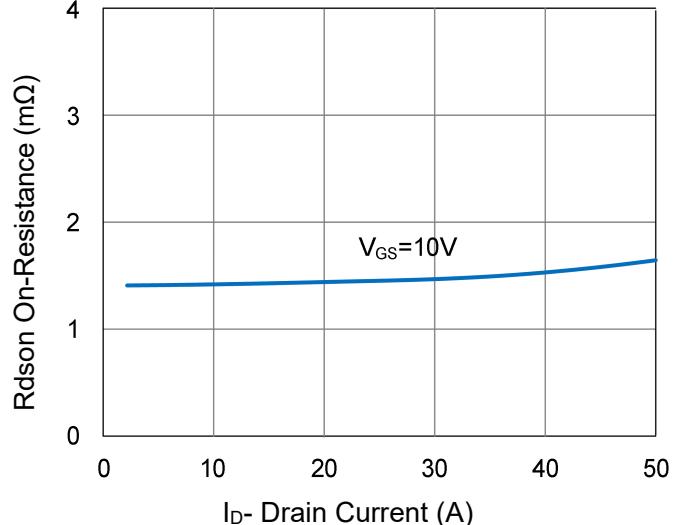
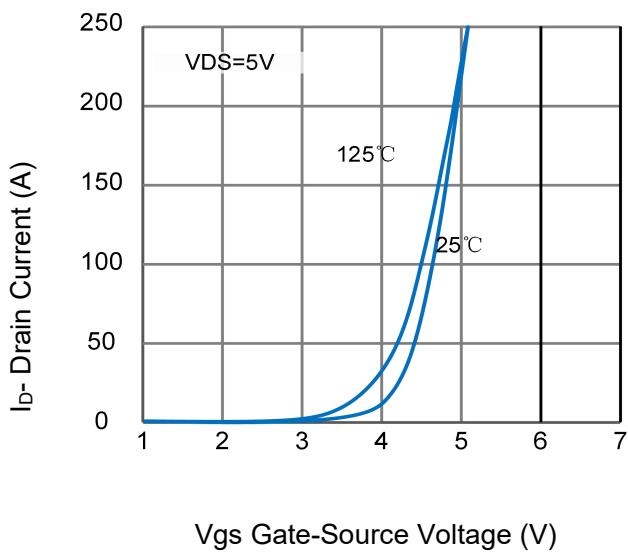
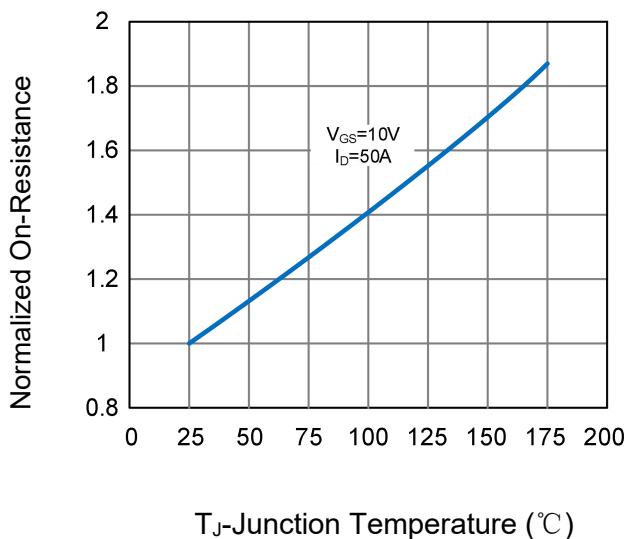
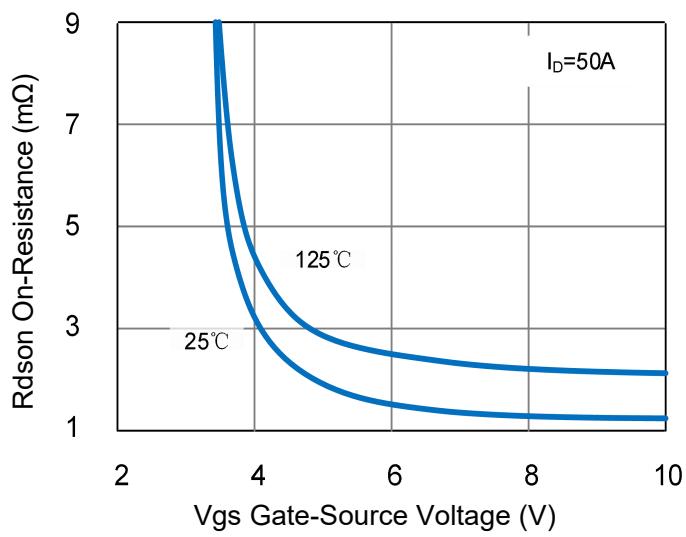
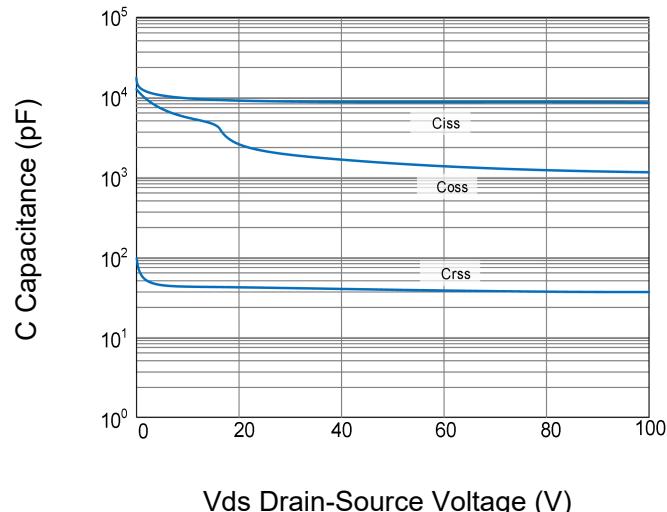
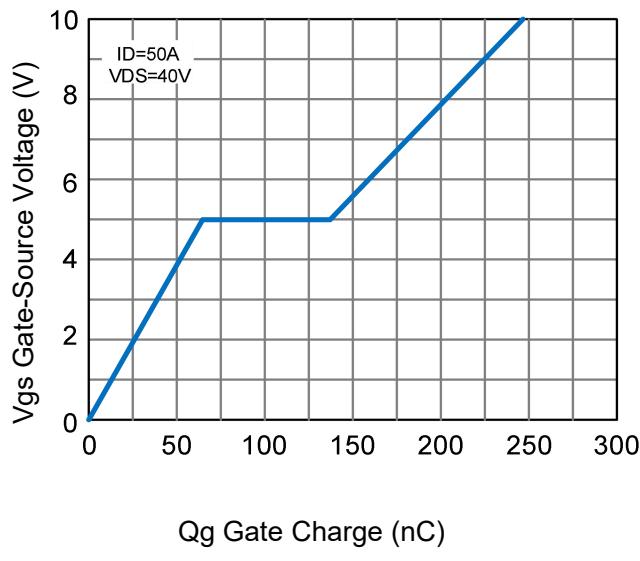
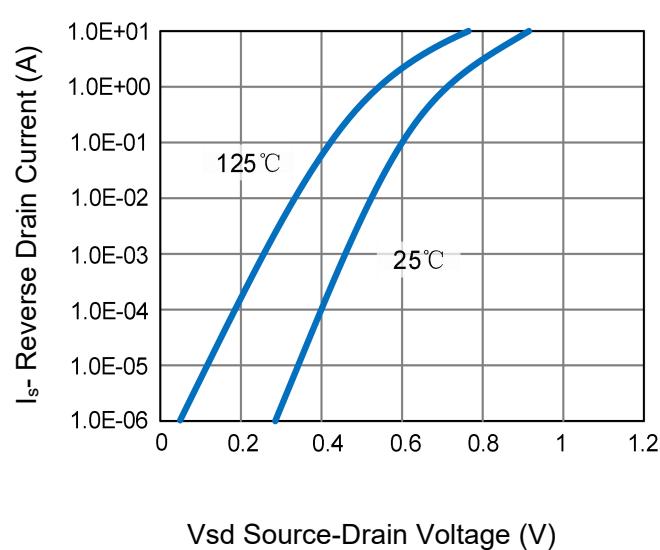


Figure 6 R_{DSON} vs Drain Current

**Figure 7 Transfer Characteristics****Figure 8 R_{dson} vs Junction Temperature****Figure 9 R_{dson} vs V_{GS}** **Figure 10 Capacitance vs V_{DS}** **Figure 11 Gate Charge****Figure 12 Source- Drain Diode Forward**

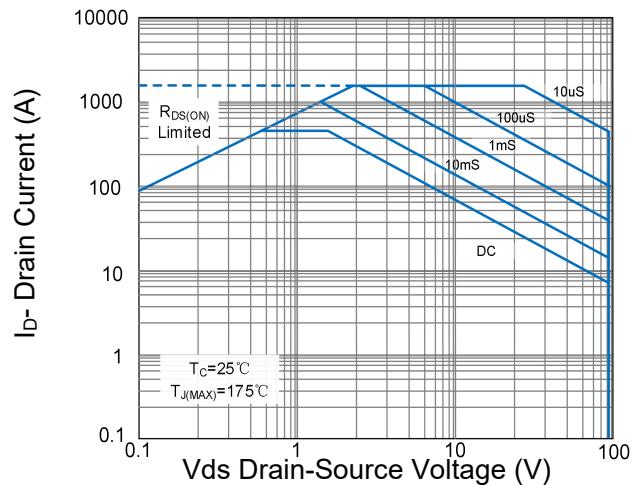


Figure 13 Safe Operation Area

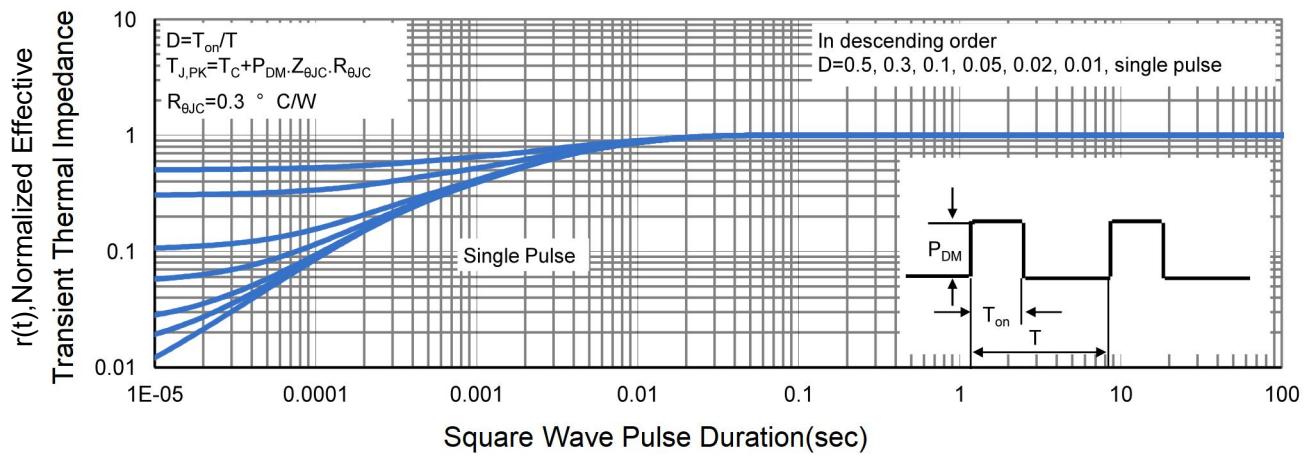
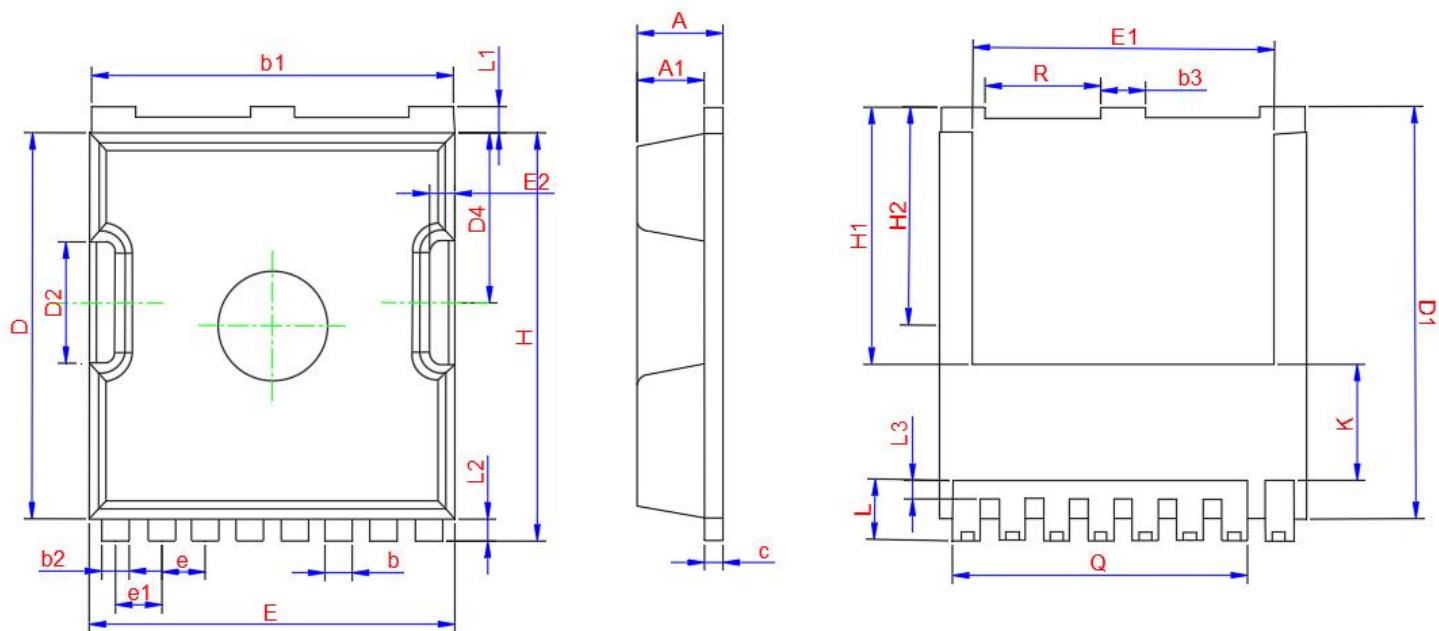


Figure 14 Normalized Maximum Transient Thermal Impedance

TOLL Package Information



| Symbol | Dimensions In Millimeters | | | Symbol | Dimensions In Millimeters | | |
|--------|---------------------------|--------|--------|--------|---------------------------|--------|--------|
| | Min. | Typ. | Max. | | Min. | Typ. | Max. |
| A | 2.200 | 2.300 | 2.400 | E2 | 0.500 | 0.600 | 0.700 |
| A1 | 1.700 | 1.800 | 1.900 | e | 1.200 BSC | | |
| b | 0.600 | 0.700 | 0.800 | e1 | 1.225 BSC | | |
| b1 | 9.700 | 9.800 | 9.900 | H | 11.600 | 11.700 | 11.800 |
| b2 | 0.650 | 0.750 | 0.850 | H1 | 6.950 BSC | | |
| b3 | 1.100 | 1.200 | 1.300 | H2 | 5.900 BSC | | |
| c | 0.400 | 0.500 | 0.600 | K | 3.100 REF. | | |
| D | 10.300 | 10.400 | 10.500 | L | 1.550 | 1.650 | 1.750 |
| D1 | 11.000 | 11.100 | 11.200 | L1 | 0.600 | 0.700 | 0.800 |
| D2 | 3.200 | 3.300 | 3.400 | L2 | 0.500 | 0.600 | 0.700 |
| D4 | 4.470 | 4.570 | 4.670 | L3 | 0.400 | 0.500 | 0.600 |
| E | 9.800 | 9.900 | 10.000 | Q | 7.950 REF. | | |
| E1 | 8.000 | 8.100 | 8.200 | R | 3.000 | 3.100 | 3.200 |